(19) World Intellectual Property Organization International Bureau



(43) International Publication Date 10 February 2005 (10.02.2005)

(10) International Publication Number WO 2005/013641 A1

(51) International Patent Classification7: H04R 1/04, 19/04

(21) International Application Number:

PCT/KR2003/001758

(22) International Filing Date: 29 August 2003 (29.08.2003)

(25) Filing Language:

Korean

(26) Publication Language:

English

(30) Priority Data: 10-2003-0052193

29 July 2003 (29.07.2003) KR

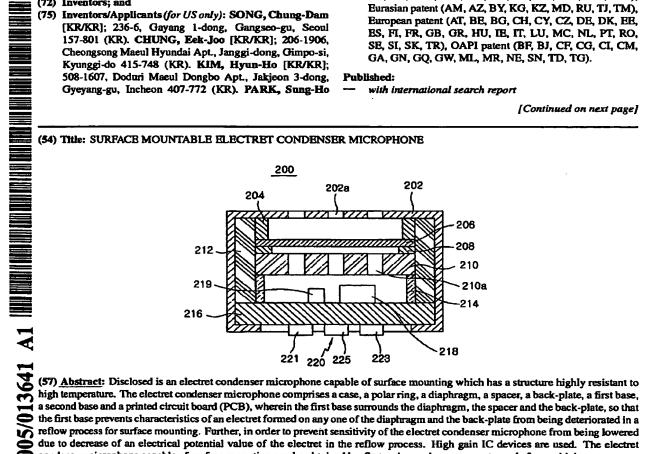
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- (81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,



reflow process for surface mounting. Further, in order to prevent sensitivity of the electret condenser microphone from being lowered due to decrease of an electrical potential value of the electret in the reflow process. High gain IC devices are used. The electret condenser microphone capable of surface mounting can be obtained by, first, using main components made from a high-temperature resistant insulating material, for example, a polymer-, a plastic- or a fluoro resin-based material, second, constructing the fist base to surround acoustic based components, third, using a cream solder for high temperature to bond components to the PCB, fourth, using the high gain IC devices, fifth, providing the connecting terminal with gas discharge grooves and protruding the connecting terminal to be higher than a curled surface of the electret condenser microphone.